

Fig. 3

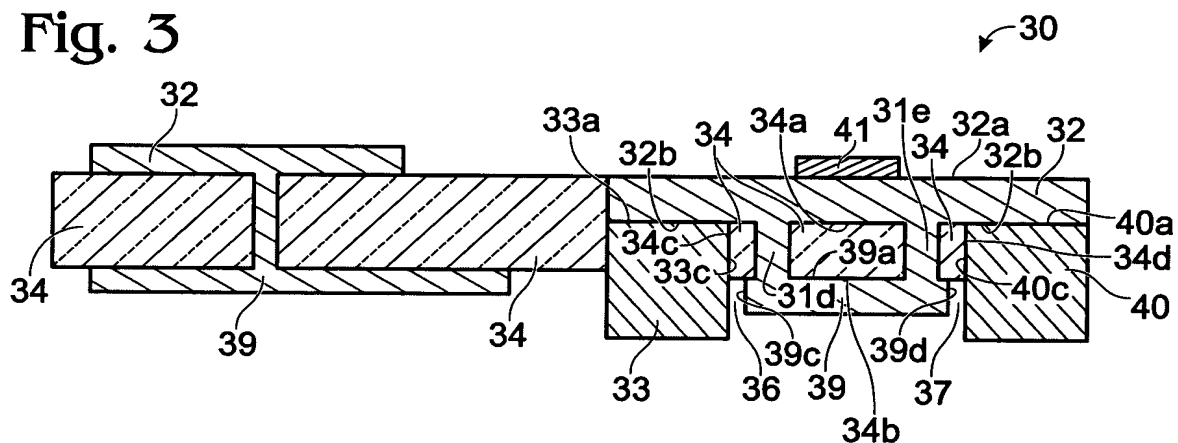
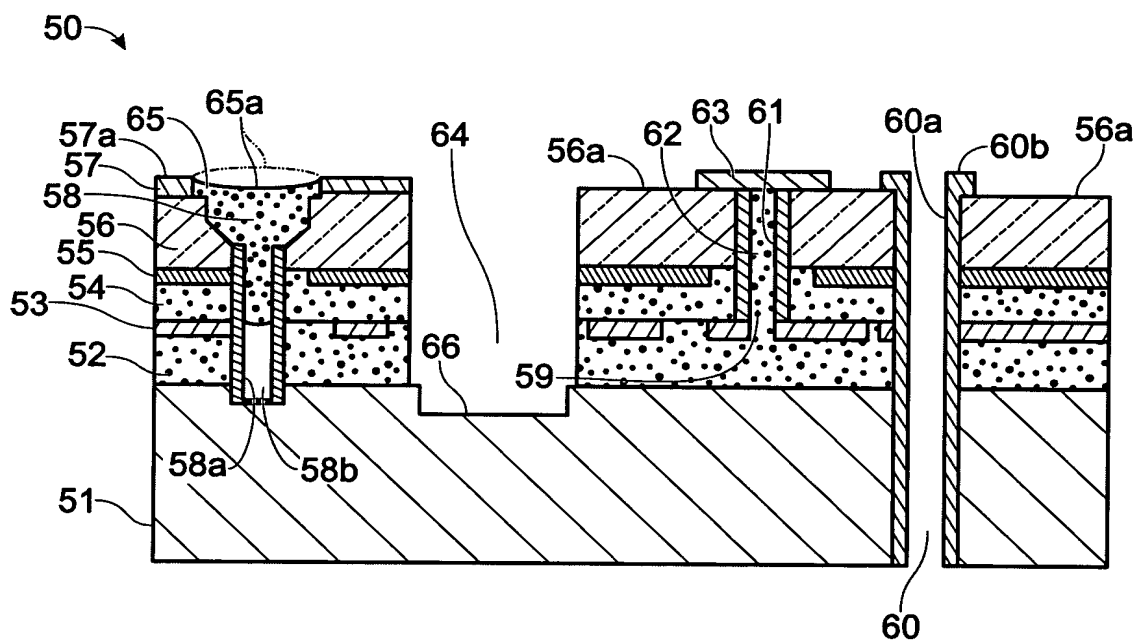
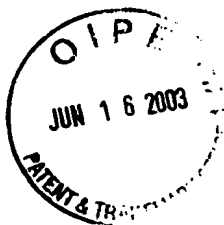


Fig. 4





Docket No. 304249  
Apparatus And Method Of Manufacturing Printed Circuit Boards  
Leo VanderWindt

**Fig. 5**

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PROCESS#	ROUTE	LAYER
6000	Material	A-bla/AL1
6900	Drilling	A-bla/AL1
7000	Plasma Etch	A-bla/AL1
7075	Black_Hole	A-bla/AL1
7150	Panel_Plating	A-bla/AL1
6130	ML lamination	A-bla/AL1
6200	ML exposure	A-bla/AL1
7400	Control_1	A-bla/AL1
7700	CU etch_1	A-bla/AL1
8000	Multibond	A-bla/AL1
6000	Material	prepreg
6700	Bondingfilm preparation	prepreg
6900	Routing_preparation	prepreg
6000	Material	backing
7700	CU Etch_1	backing
8800	Routing 4-Slots	backing
6900	Routing_preparation	backing
6600	Multibond	backing
6700	ML pressing	total construction
6900	Depth drilling_1	total construction
8800	Depth routing_2	total construction
7000	Plasma Etch	total construction
7075	Black_Hole	total construction
7200	Lamination_Outerlayers	total construction
7300	Exposure outerlayers	total construction
7400	control_1	total construction
7500	Plating_Cu + PbSn	total construction
7700	Kooper Etch_1	total construction
7800	PbSn_strip	total construction
6900	Depth drilling_1	total construction
8800	Depth routing	total construction
6900	Drilling	total construction
7400	100% visual inspection	total construction
8550	Chem Ni/Au	total construction
8100	Via's Plugging	total construction
8200	Soldmask_Coaten2 DP 2500	total construction
8500	Component identification	total construction
6900	Routing preparation	total construction
8800	Post treatment routing	total construction
8700	Bare board testing	total construction
8900	Final inspection	total construction